

ABSTRACT

Winding Structure of Bonding Wire for Semiconductor Application

[Problem to be solved] To provide a winding form of a bonding wire by which the bonding wire hardly causes springs back and does not loosen so much on a spool even when being cut.

[Solution] This invention relates to a winding structure of a winding ending end part (an earth part upon wire feeding) of a main winding part of the bonding wire wound around a wire winding part of a spool barrel, the winding structure comprising one layer structured such that earth wires are wound in contact with each other on the spool barrel and in arrays, and a plurality of wires are pressed dispersedly in columns and arrayed in highly close contact.

[Selected Drawing] Fig. 2